

I claim

1. A semiconductor device by embedded package, comprising:

a nail head having a bonding end and a leading conductor; and

a metal housing having a cavity therein; wherein

5 a bonding stage is formed on the metal housing within the cavity;

a semiconductor chip is installed on the bonding stage with two sides
connected to the nail head and the bonding stage, respectively;

the bonding stage has a fence at an edge thereof;

a well is formed around the bonding stage inside the cavity thereof; and

10 the metal housing has a inner side wall around the well and enclosing the
cavity.

2. The semiconductor device by embedded package as claimed in claim 1,
wherein the fence slantingly extends from side of bonding stage to side of an

15 inner sidewall thereof.

3. The semiconductor device by embedded package as claimed in claim 1,
wherein the semiconductor chip is surrounded by the insulation glue and the
insulation glue is constrained by the fence.

20

4. The semiconductor device by embedded package as claimed in claim 1,
wherein the cavity is filled with the buffer material.